

# Product / Process Change Notification



N° 2016-059-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## **Change of assembly location to Amkor Philippines and wafer fab and wafer test location to Infineon Kulim Malaysia affecting TLE8250G and TLE8250GVIO**

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **6. September 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "**JESD46**", which stipulates: "**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**"
- **Please note that this PCN together with PCN 2016-058-A replaces the cancelled PCN 2014-058-X.**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Wolfgang Mayrhuber  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

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► Products affected:	Sales Name	SP N°	OPN	Package
	TLE8250G	SP000551642	TLE8250GXUMA1	PG-DSO-8
	TLE8250GVIO	SP000691818	TLE8250GVIOXUMA1	PG-DSO-8

## ► Detailed Change Information:

**Subject:** Change of assembly location to Amkor Philippines and implementation of AMKOR's standard automotive Bill of Material (BoM) and change of wafer fab and wafer test location to Infineon Kulim Malaysia affecting TLE8250G and TLE8250GVIO.

**Reason:** Due to continuously raising demand for Infineon automotive products we are going to introduce the package subcontractor Amkor Technologies, Philippines as a new assembly location and the well-known Infineon front-end location Kulim as new wafer fab and wafer test location.  
Amkor Philippines, using state-of-the-art bill of material (BoM), has a long term experience as automotive assembler for Infineon and is TS16949 certified and Infineon robust and green qualified.

Description:	<u>Old</u>	<u>New</u>
<b>Wafer fab location</b>	<ul style="list-style-type: none"> <li>Infineon Technologies AG, Regensburg, Germany</li> </ul>	<ul style="list-style-type: none"> <li>Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia</li> </ul>
<b>Wafer test location</b>	<ul style="list-style-type: none"> <li>Infineon Technologies AG, Villach, Germany</li> </ul>	<ul style="list-style-type: none"> <li>Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia</li> </ul>
<b>Assembly location</b>	<ul style="list-style-type: none"> <li>Infineon Technologies, Malacca, Malaysia</li> </ul>	<ul style="list-style-type: none"> <li>Amkor Philippines</li> </ul>
<b>Bill of Material (BoM)</b>	<ul style="list-style-type: none"> <li>Infineon robust-green BoM</li> </ul>	<ul style="list-style-type: none"> <li>Amkor automotive green standard BoM</li> </ul>
<b>MSL</b>	<ul style="list-style-type: none"> <li>3</li> </ul>	<ul style="list-style-type: none"> <li>2a</li> </ul>

**► Product Identification:**

- New SP/OPN number
- For Amkor packages: mold location number on package backside.

**► Impact of Change:**

There is no change in form, fit, function and electrical performance. Quality and reliability verified by qualification. The device dimensions will remain unchanged.  
We are able to improve MSL capability from MSL3 to MSL2a.  
Wafer fab and wafer test in KULIM are qualified for similar products in the same technology already.  
The final test location will remain unchanged at Infineon.

**► Attachments:** N.A.

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## ► Time Schedule:

■ Final qualification report:	Available
■ First samples available:	Available
■ Intended start of delivery:	01-January-2017 or earlier after customer release

### Refer to page 4/4:

■ Last order date of unchanged product:	31-December-2016
■ Last delivery date of unchanged product:	30-June-2017

If you have any questions, please do not hesitate to contact your local Sales office.

# PRODUCT REPLACEMENT



Referring to PCN N° 2016-059-A

■ Last order date of unchanged product:	2016-12-31
■ Last delivery date of unchanged product:	2017-06-30

CURRENT				NEW (REPLACEMENT)			
Device	Ordering Code	OPN	Package	Device	Ordering Code	OPN	Package
TLE8250G	SP000551642	TLE8250GXUMA1	PG-DSO-8	TLE8250G	SP001428740	TLE8250GXUMA5	PG-DSO-8
TLE8250GVIO	SP000691818	TLE8250GVIOXUMA1	PG-DSO-8	TLE8250GVIO	SP001428742	TLE8250GVIOXUMA5	PG-DSO-8